



COPY OF PAPERS
ORIGINALLY FILED

#12e
amult
hchpmm
8-7-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

WARREN M. FARNWORTH
SALMAN AKRAM

Serial No.: 09/844,532

Filing Date: April 30, 2001

RECEIVED
JUL 26 2002
TECHNOLOGICAL
EXAMINER: Chang, R.
EXAM CENTER R3706
Art Unit: 3729

For: METHOD FOR FABRICATING A TEST INTERCONNECT FOR BUMPED
SEMICONDUCTOR COMPONENTS BY FORMING RECESSES AND
CANTILIVERED LEADS ON A SUBSTRATE (AS AMENDED)

Attorney Docket No. 97-1433.1

AMENDMENT
July 15, 2002

Assistant Commissioner of Patents
BOX AMENDMENT (FEE)
Washington, DC 20231

Sir:

This Amendment is a Response to the Office Action dated March 29, 2002 having a statutory period for response set to expire on July 1, 2002, but extended for thirty days by the attached Petition For Extension Of Time until July 29, 2002. Please amend the case as follows.

In the Specification

Please change the title to Method For Fabricating A Test Interconnect For Bumped Semiconductor Components By Forming Recesses And Cantilevered Leads On A Substrate--.

Following is a clean version of an amended Abstract. In addition, a marked version identifying the changes to the original Abstract follows the Remarks section of this Amendment.